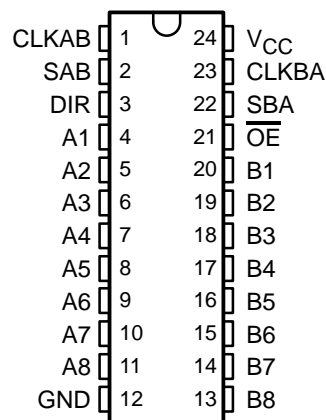


# CD54HC646, CD74HCT646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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- 2-V to 6-V  $V_{CC}$  Operation (CD54HC646)
- 4.5-V to 5.5-V  $V_{CC}$  Operation (CD74HCT646)
- Wide Operating Temperature Range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$
- Balanced Propagation Delays and Transition Times
- Standard Outputs Drive Up To 15 LS-TTL Loads
- Significant Power Reduction Compared to LS-TTL Logic ICs
- Inputs Are TTL-Voltage Compatible (CD74HCT646)
- Independent Registers for A and B Buses
- Multiplexed Real-Time and Stored Data
- True Data Paths

CD54HC646 . . . F PACKAGE  
CD74HCT646 . . . M PACKAGE  
(TOP VIEW)



## description/ordering information

The CD54HC646 and CD74HCT646 consist of bus-transceiver circuits with 3-state outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with these devices.

Output-enable ( $\overline{\text{OE}}$ ) and direction-control (DIR) inputs control the transceiver functions. In the transceiver mode, data present at the high-impedance port can be stored in either or both registers.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. DIR determines which bus receives data when  $\overline{\text{OE}}$  is active (low). In the isolation mode ( $\overline{\text{OE}}$  high), A data can be stored in one register and/or B data can be stored in the other register.

When an output function is disabled, the input function still is enabled and can be used to store data. Only one of the two buses, A or B, can be driven at a time.

To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
$-55^{\circ}\text{C}$ to $125^{\circ}\text{C}$	SOIC – M	Tape and reel	CD74HCT646M96	HCT646M
	CDIP – F	Tube	CD54HC646F3A	CD54HC646F3A

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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**CD54HC646, CD74HCT646**  
**OCTAL BUS TRANSCEIVERS AND REGISTERS**  
**WITH 3-STATE OUTPUTS**

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**FUNCTION TABLE**

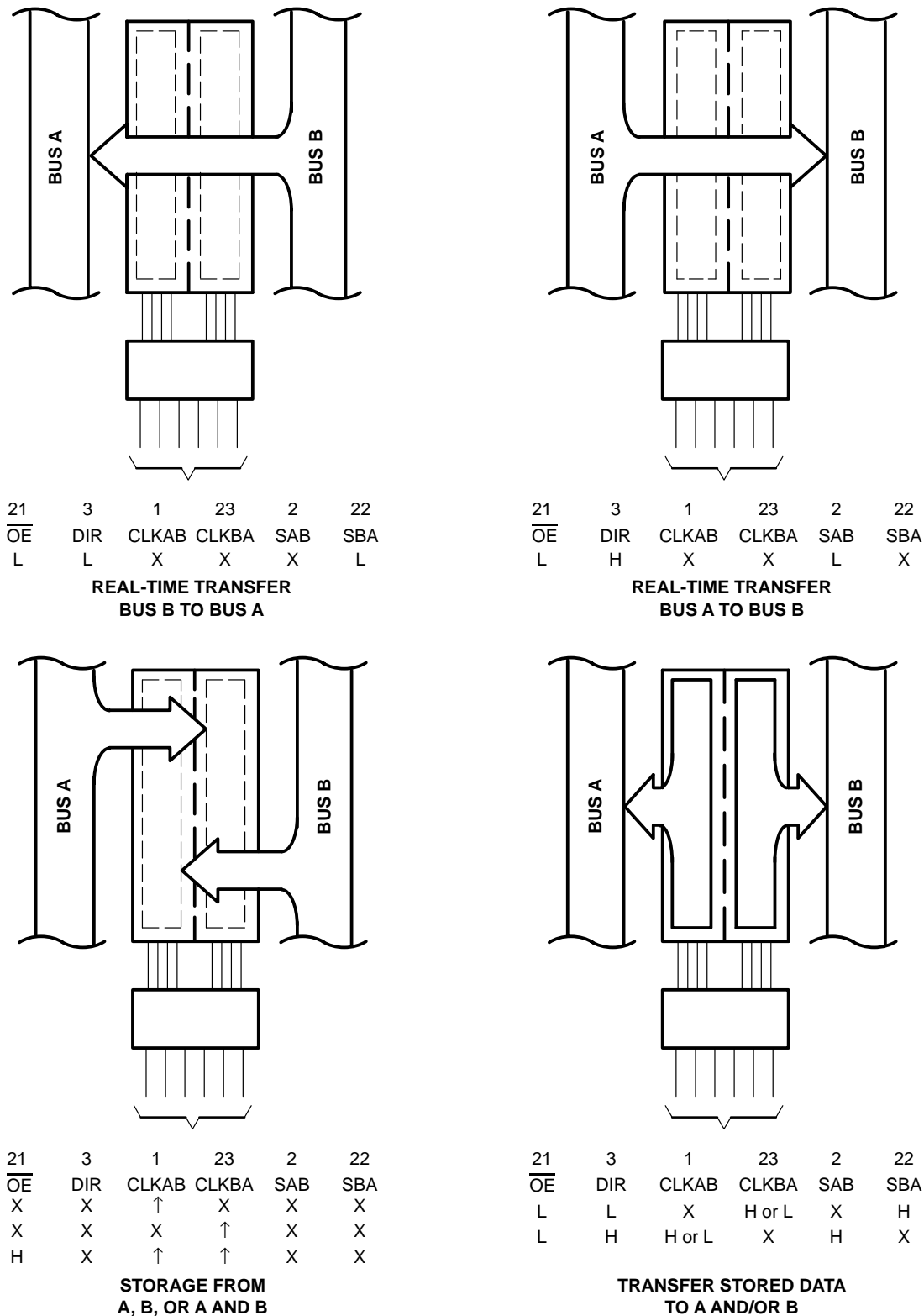
INPUTS						DATA I/O		OPERATION OR FUNCTION
$\overline{OE}$	DIR	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	
X	X	↑	X	X	X	Input	Unspecified†	Store A, B unspecified†
X	X	X	↑	X	X	Unspecified†	Input	Store B, A unspecified†
H	X	↑	↑	X	X	Input	Input	Store A and B data
H	X	H or L	H or L	X	X	Input disabled	Input disabled	Isolation, hold storage
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
L	H	X	X	L	X	Input	Output	Real-time A data to B bus
L	H	H or L	X	H	X	Input	Output	Stored A data to B bus

† The data-output functions can be enabled or disabled by various signals at  $\overline{OE}$  and DIR. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



**CD54HC646, CD74HCT646**  
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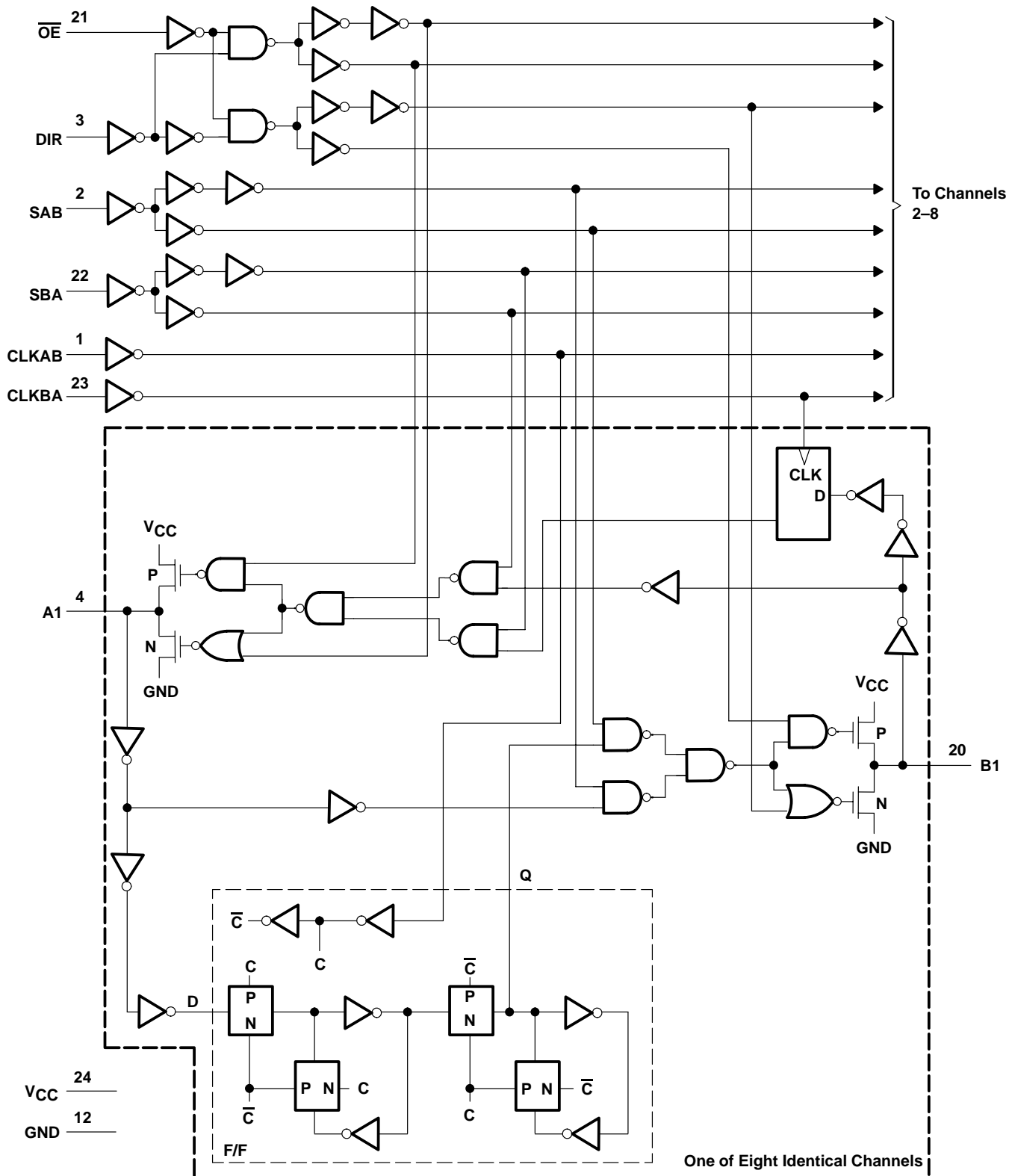


**Figure 1. Bus-Management Functions**

# CD54HC646, CD74HCT646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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## logic diagram (positive logic)



# CD54HC646, CD74HCT646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	–0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1) .....	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1) .....	±20 mA
Continuous output drain current per output, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	±35 mA
Continuous current through $V_{CC}$ or GND .....	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2) M package .....	46°C/W
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions for CD54HC646 (see Note 3)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	2	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2$ V	1.5	V
		$V_{CC} = 4.5$ V	3.15	
		$V_{CC} = 6$ V	4.2	
$V_{IL}$	Low-level input voltage	$V_{CC} = 2$ V	0.5	V
		$V_{CC} = 4.5$ V	1.35	
		$V_{CC} = 6$ V	1.8	
$V_I$	Input voltage	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	V
$t_t$	Input transition (rise and fall) time	$V_{CC} = 2$ V	1000	ns
		$V_{CC} = 4.5$ V	500	
		$V_{CC} = 6$ V	400	
$T_A$	Operating free-air temperature	–55	125	°C

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## recommended operating conditions for CD74HCT646 (see Note 3)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	4.5	5.5	V
$V_{IH}$	High-level input voltage	2		V
$V_{IL}$	Low-level input voltage		0.8	V
$V_I$	Input voltage		$V_{CC}$	V
$V_O$	Output voltage		$V_{CC}$	V
$t_t$	Input transition (rise and fall) time		500	ns
$T_A$	Operating free-air temperature	–55	125	°C

NOTE 4: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



**CD54HC646, CD74HCT646**  
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**electrical characteristics for CD54HC646 over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C		T <sub>A</sub> = -55°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2 V	1.9		1.9		1.9		V
			4.5 V	4.4		4.4		4.4		
			6 V	5.9		5.9		5.9		
		I <sub>OH</sub> = -6 mA	4.5 V	3.98		3.7		3.84		
		I <sub>OH</sub> = -7.8 mA	6 V	5.48		5.2		5.34		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V		0.1		0.1		0.1	V
			4.5 V		0.1		0.1		0.1	
			6 V		0.1		0.1		0.1	
		I <sub>OL</sub> = 6 mA	4.5 V		0.26		0.4		0.33	
		I <sub>OL</sub> = 7.8 mA	6 V		0.26		0.4		0.33	
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0		6 V		±0.1		±1		±1	μA
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or 0		6 V		±0.5		±10		±5	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0		6 V		8		160		80	μA
C <sub>i</sub>					10		10		10	pF
C <sub>o</sub>					20		20		20	pF

**electrical characteristics for CD74HCT646 over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	4.5 V	4.4			4.4		4.4	V	
		I <sub>OH</sub> = -6 mA		3.98			3.7		3.84		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	4.5 V		0.1		0.1		0.1	V	
		I <sub>OL</sub> = 6 mA			0.26		0.4		0.33		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> to GND		5.5 V		±0.1		±1		±1	μA	
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or 0		5.5 V		±0.5		±10		±5	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0		5.5 V		8		160		80	μA	
ΔI <sub>CC</sub> †	One input at V <sub>CC</sub> - 2.1 V, Other inputs at 0 or V <sub>CC</sub>		4.5 V to 5.5 V		100	360		490		450	μA
C <sub>i</sub>					10		10		10	pF	
C <sub>o</sub>					20		20		20	pF	

† Additional quiescent supply current per input pin, TTL inputs high, 1 unit load



# CD54HC646, CD74HCT646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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**HCT INPUT LOADING TABLE**

INPUT	UNIT LOAD†
$\overline{OE}$	1.3
DIR	0.75
CLKAB or CLKBA	0.6
SAB or SBA	0.45
A or B	0.3

† Unit Load is  $\Delta I_{CC}$  limit specified in electrical characteristics table (e.g., 360  $\mu$ A max at 25°C).

**timing requirements for CD54HC646 over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)**

	$V_{CC}$	$T_A = 25^\circ\text{C}$		$T_A = -55^\circ\text{C}$ TO $125^\circ\text{C}$		$T_A = -40^\circ\text{C}$ TO $85^\circ\text{C}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
$f_{\text{clock}}$ Clock frequency	2 V		6		4		5	MHz
	4.5 V		30		20		25	
	6 V		35		23		29	
$t_w$ Pulse duration, CLKBA or CLKAB high or low	2 V		80		120		100	ns
	4.5 V		16		24		20	
	6 V		14		20		17	
$t_{su}$ Setup time, A before CLKAB $\uparrow$ or B before CLKBA $\uparrow$	2 V		60		90		75	ns
	4.5 V		12		18		15	
	6 V		10		15		13	
$t_h$ Hold time, A after CLKAB $\uparrow$ or B after CLKBA $\uparrow$	2 V		35		55		45	ns
	4.5 V		7		11		9	
	6 V		6		9		8	

**timing requirements for CD74HCT646 over recommended operating free-air temperature range,  $V_{CC} = 4.5$  V (unless otherwise noted) (see Figure 3)**

	$T_A = 25^\circ\text{C}$		$T_A = -55^\circ\text{C}$ TO $125^\circ\text{C}$		$T_A = -40^\circ\text{C}$ TO $85^\circ\text{C}$		UNIT
	MIN	MAX	MIN	MAX	MIN	MAX	
$f_{\text{clock}}$ Clock frequency		25		17		20	MHz
$t_w$ Pulse duration, CLKBA or CLKAB high or low		25		38		31	ns
$t_{su}$ Setup time, A before CLKAB $\uparrow$ or B before CLKBA $\uparrow$		12		18		15	ns
$t_h$ Hold time, A after CLKAB $\uparrow$ or B after CLKBA $\uparrow$		5		5		5	ns

**CD54HC646, CD74HCT646**  
**OCTAL BUS TRANSCEIVERS AND REGISTERS**  
**WITH 3-STATE OUTPUTS**

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**switching characteristics for CD54HC646 over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT	
					MIN	TYP	MAX	MIN	MAX	MIN	MAX		
f <sub>max</sub>			C <sub>L</sub> = 50 pF	2 V	6			4		5	MHz		
				4.5 V	30			20		25			
				6 V	35			23		29			
			C <sub>L</sub> = 15 pF	5 V	60								
t <sub>pd</sub>	CLKBA or CLKAB	A or B	C <sub>L</sub> = 50 pF	2 V		220		330		275	ns		
				4.5 V		44		66		55			
				6 V		37		56		47			
			C <sub>L</sub> = 15 pF	5 V	18								
	A or B	B or A	C <sub>L</sub> = 50 pF	2 V		135		205		170			
				4.5 V		27		41		34			
				6 V		23		35		29			
			C <sub>L</sub> = 15 pF	5 V	12								
			SBA or SAB†	A or B	C <sub>L</sub> = 50 pF	2 V		170		255			215
						4.5 V		34		51			43
	6 V					29		43		37			
	C <sub>L</sub> = 15 pF	5 V			14								
t <sub>en</sub>	$\overline{\text{OE}}$	A or B	C <sub>L</sub> = 50 pF	2 V		175		265		220			
				4.5 V		35		53		44			
				6 V		30		45		37			
			C <sub>L</sub> = 15 pF	5 V	14								
t <sub>dis</sub>	$\overline{\text{OE}}$	A or B	C <sub>L</sub> = 50 pF	2 V		175		265		220			
				4.5 V		35		53		44			
				6 V		30		45		37			
			C <sub>L</sub> = 15 pF	5 V	14								
t <sub>t</sub>		Any	C <sub>L</sub> = 50 pF	2 V		60		90		75			
				4.5 V		12		18		15			
				6 V		10		15		13			

† These parameters are measured with the internal output state of the storage register opposite that of the bus input.





**CD54HC646, CD74HCT646**  
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**WITH 3-STATE OUTPUTS**

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**switching characteristics for CD74HCT646 over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT
					MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			C <sub>L</sub> = 50 pF	4.5 V	25			17		20	MHz	
			C <sub>L</sub> = 15 pF	5 V		45						
t <sub>pd</sub>	CLKBA or CLKAB	A or B	C <sub>L</sub> = 50 pF	4.5 V			44		66	55	ns	
			C <sub>L</sub> = 15 pF	5 V		18						
	A or B	B or A	C <sub>L</sub> = 50 pF	4.5 V			37		56	46		
			C <sub>L</sub> = 15 pF	5 V		15						
	SBA or SAB†	A or B	C <sub>L</sub> = 50 pF	4.5 V			46		69	58		
			C <sub>L</sub> = 15 pF	5 V		19						
t <sub>en</sub>	$\overline{OE}$	A or B	C <sub>L</sub> = 50 pF	4.5 V			45		68	56	ns	
			C <sub>L</sub> = 15 pF	5 V		19						
t <sub>dis</sub>	$\overline{OE}$	A or B	C <sub>L</sub> = 50 pF	4.5 V			35		53	44	ns	
			C <sub>L</sub> = 15 pF	5 V		14						
t <sub>t</sub>			C <sub>L</sub> = 50 pF	4.5 V			12		18	15	ns	

† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

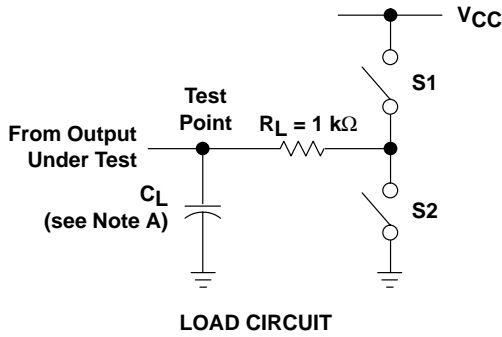
**operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C**

PARAMETER	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	52	pF

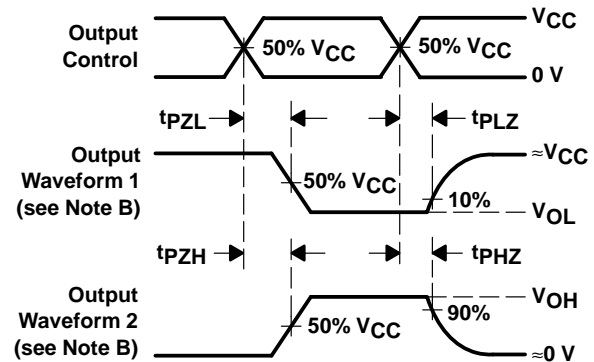
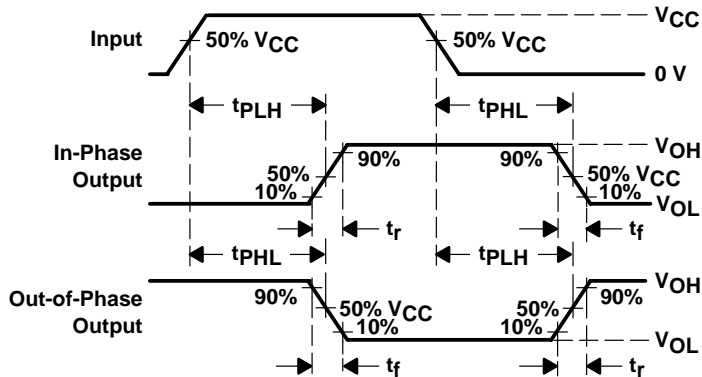
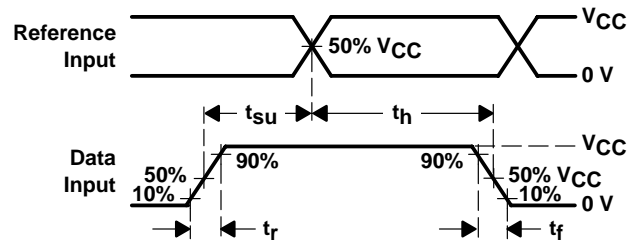
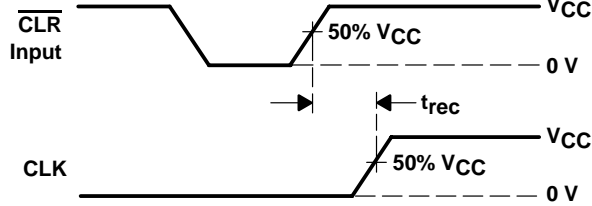
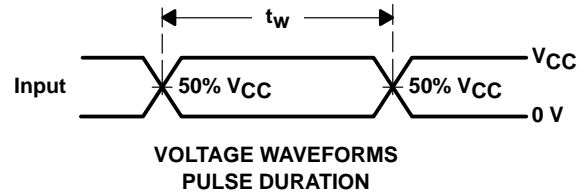
# CD54HC646, CD74HCT646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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## PARAMETER MEASUREMENT INFORMATION – CD54HC646



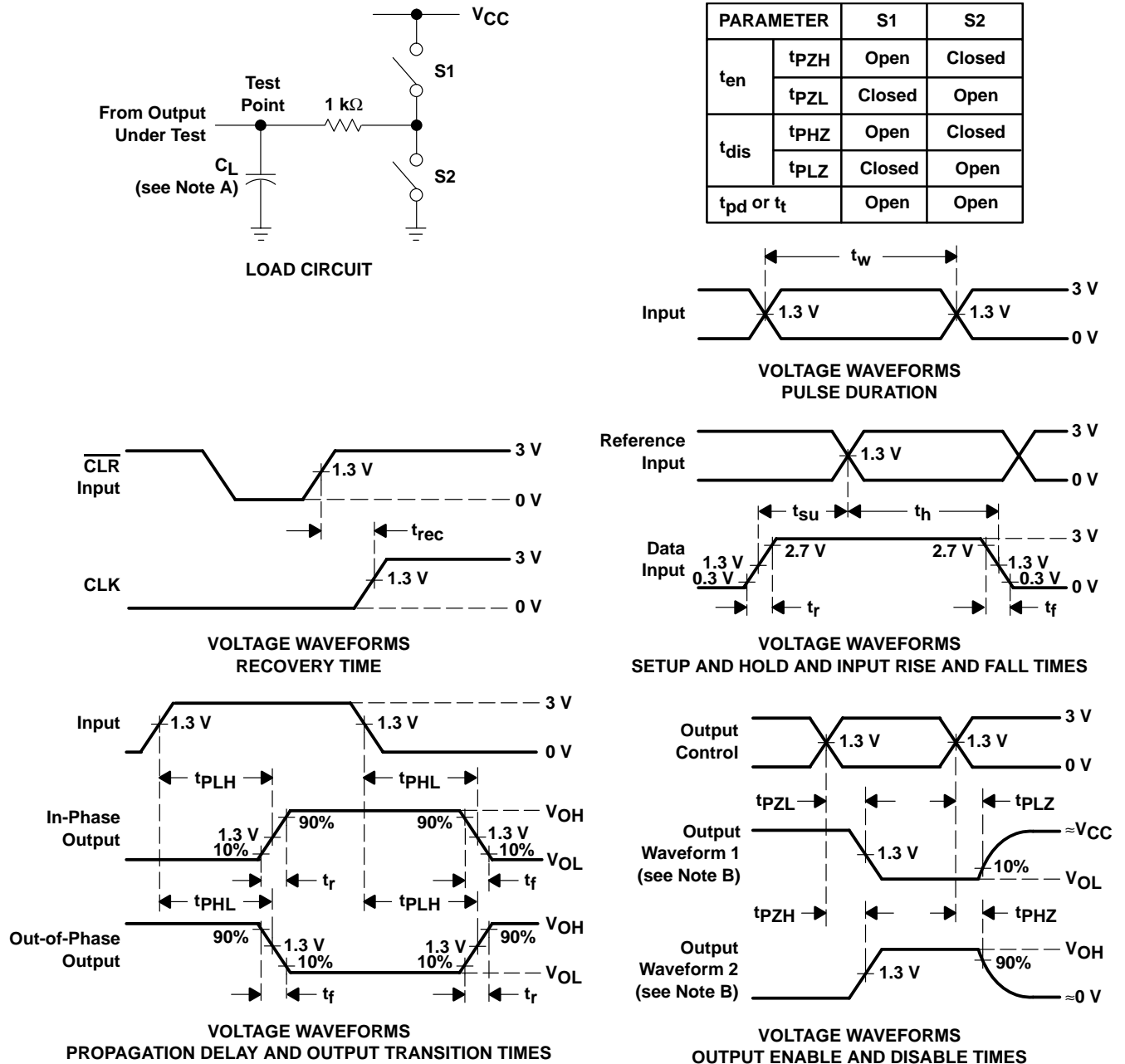
PARAMETER	S1	S2	
$t_{en}$	tPZH	Open	Closed
	tPZL	Closed	Open
$t_{dis}$	tPHZ	Open	Closed
	tPLZ	Closed	Open
$t_{pd}$ or $t_t$	Open	Open	



- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r = 6\text{ ns}$ ,  $t_f = 6\text{ ns}$ .  
 D. For clock inputs,  $f_{max}$  is measured with the input duty cycle at 50%.  
 E. The outputs are measured one at a time with one input transition per measurement.  
 F.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 G.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 H.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 2. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION – CD74HCT646



- NOTES:
- A.  $C_L$  includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.
  - D. For clock inputs,  $f_{max}$  is measured with the input duty cycle at 50%.
  - E. The outputs are measured one at a time with one input transition per measurement.
  - F.  $t_{pLZ}$  and  $t_{pHZ}$  are the same as  $t_{dis}$ .
  - G.  $t_{pZL}$  and  $t_{pZH}$  are the same as  $t_{en}$ .
  - H.  $t_{pLH}$  and  $t_{pHL}$  are the same as  $t_{pd}$ .

Figure 3. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8688501JA	ACTIVE	CDIP	J	24	1	Non-RoHS & Non-Green	Call TI	N / A for Pkg Type	-55 to 125	5962-8688501JA CD54HC646F3A	<a href="#">Samples</a>
CD54HC646F3A	ACTIVE	CDIP	J	24	1	Non-RoHS & Non-Green	Call TI	N / A for Pkg Type	-55 to 125	5962-8688501JA CD54HC646F3A	<a href="#">Samples</a>
CD74HCT646M96	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT646M	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HCT646M96	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HCT646M96	SOIC	DW	24	2000	350.0	350.0	43.0

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



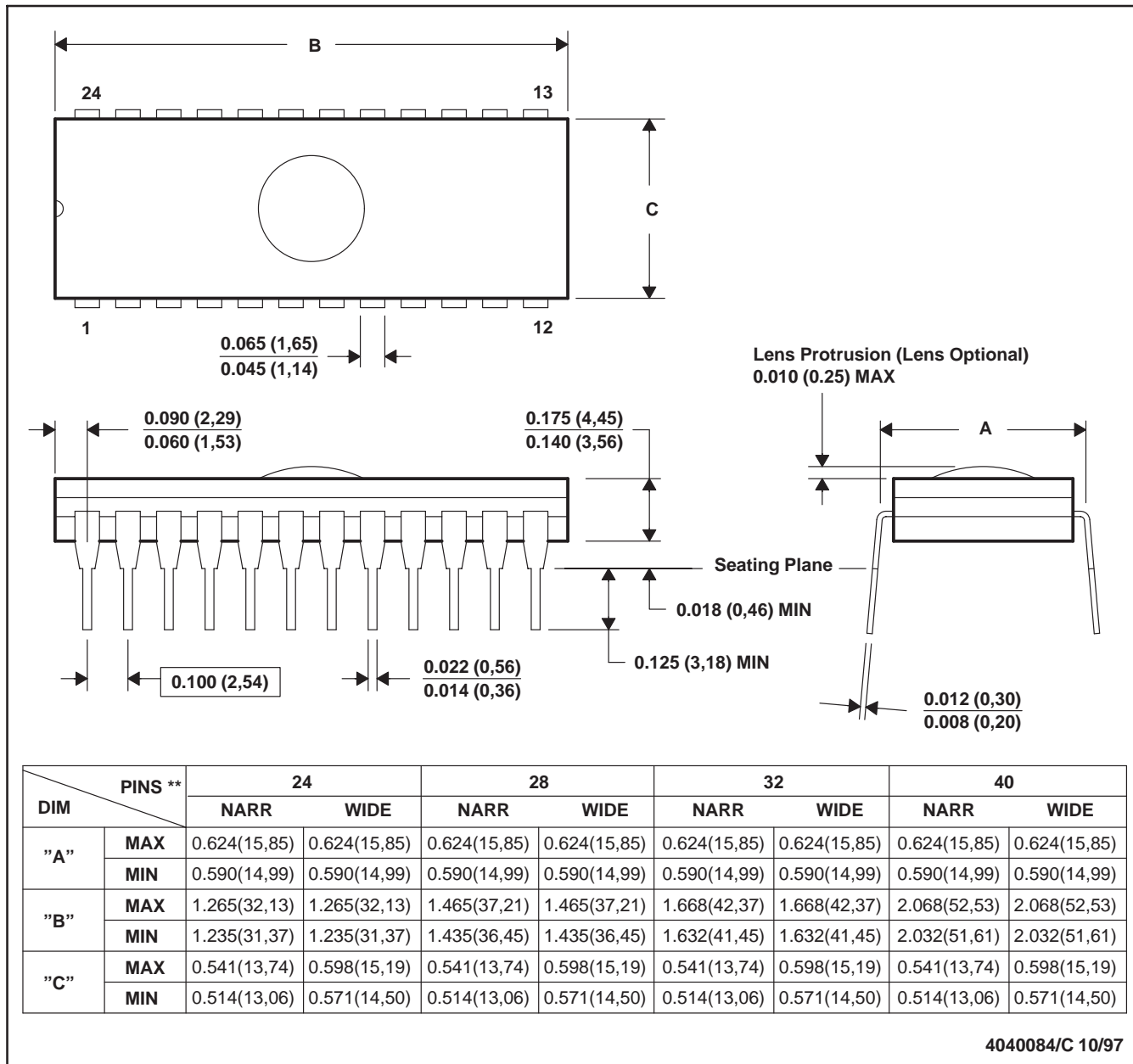
- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AD.



J (R-GDIP-T\*\*)

CERAMIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).  
 D. This package can be hermetically sealed with a ceramic lid using glass frit.  
 E. Index point is provided on cap for terminal identification.

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